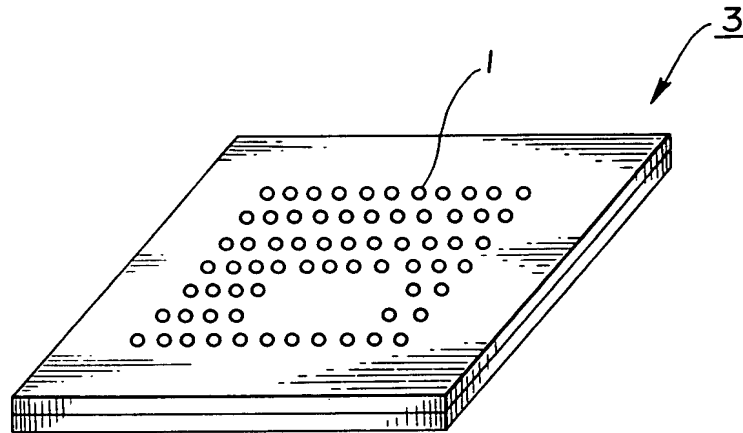


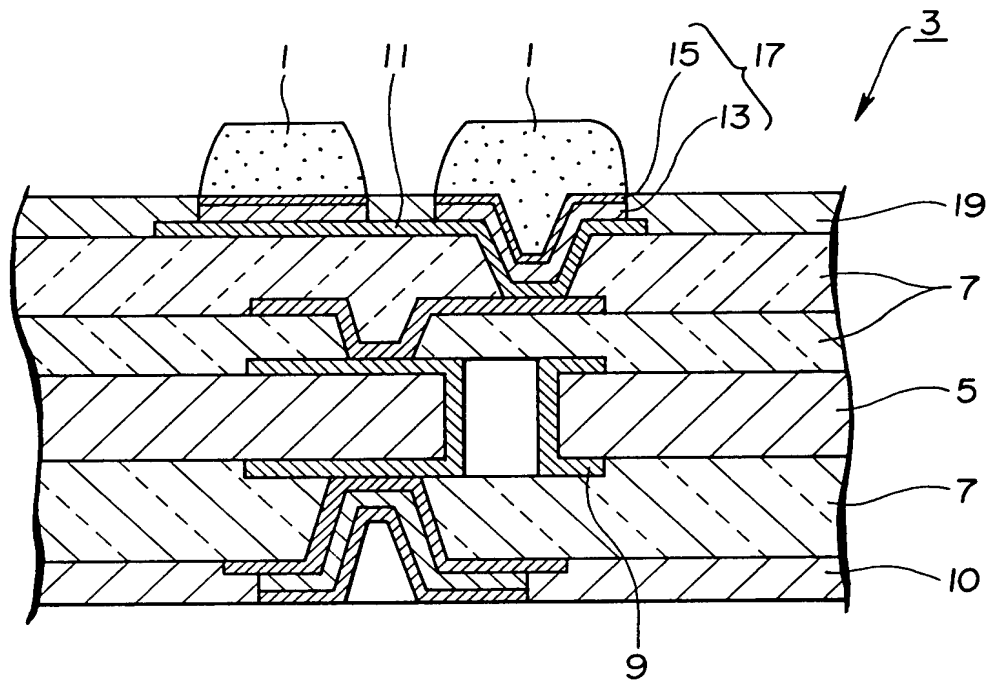


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**FIG.1A**

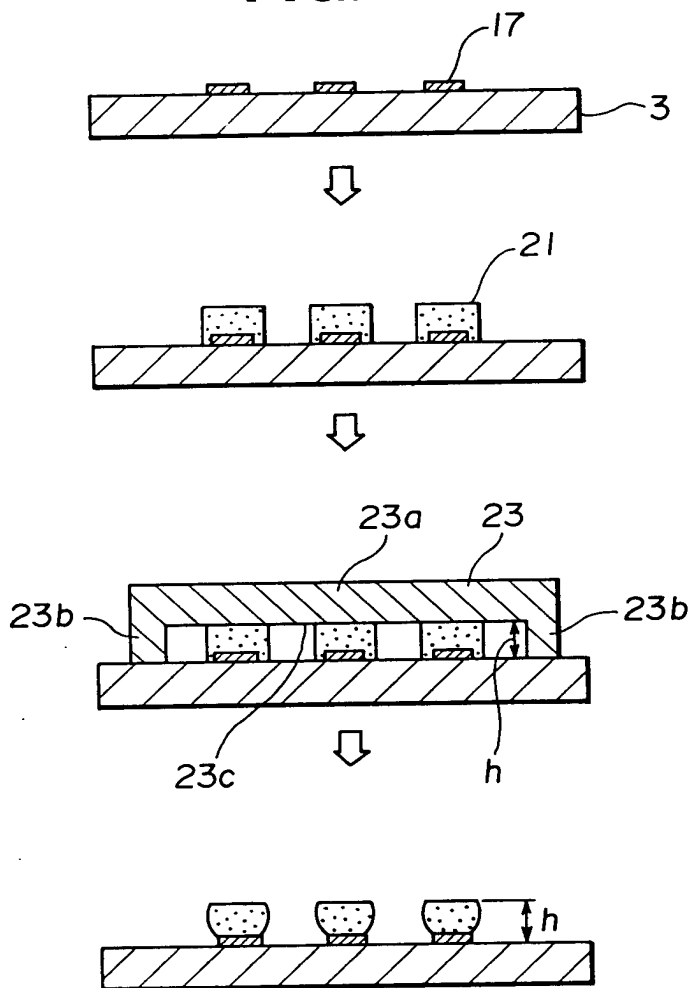


**FIG.1B**

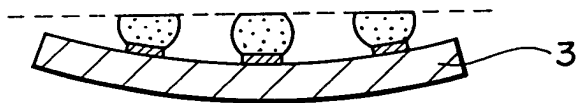




**FIG.2A**



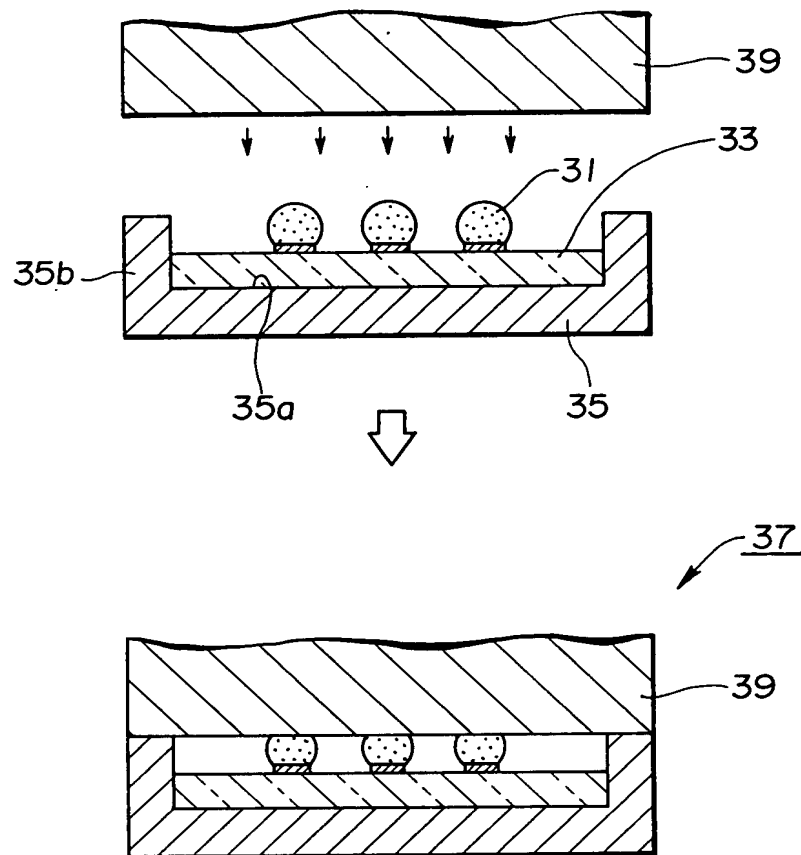
**FIG.2B**





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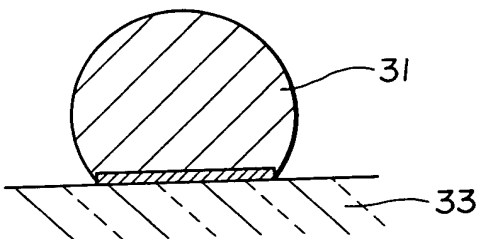
**FIG.3**



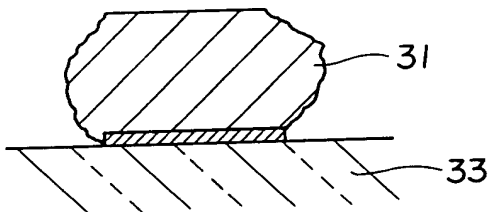


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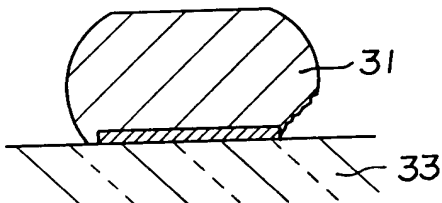
**FIG.4A**



**FIG.4B**



**FIG.4C**





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**FIG.5**

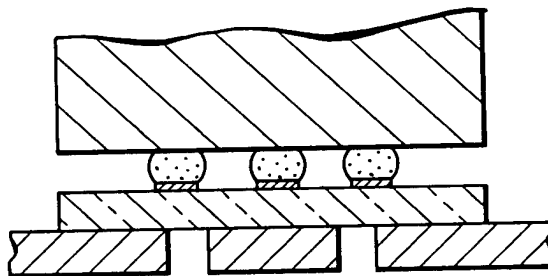
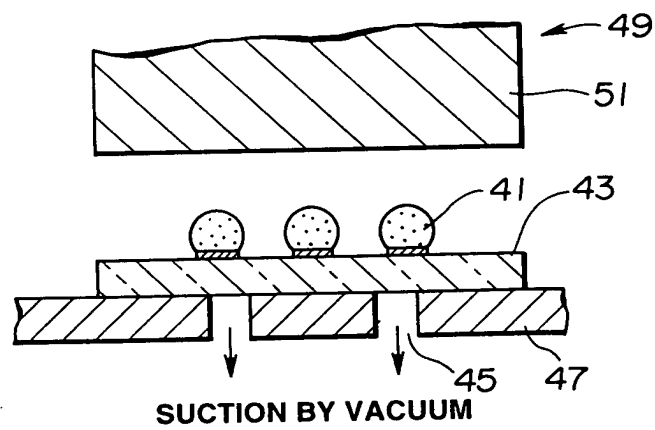




FIG.6

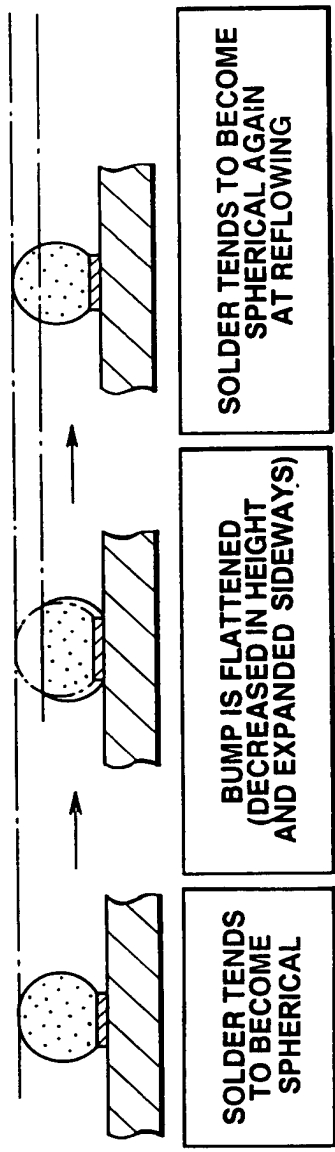
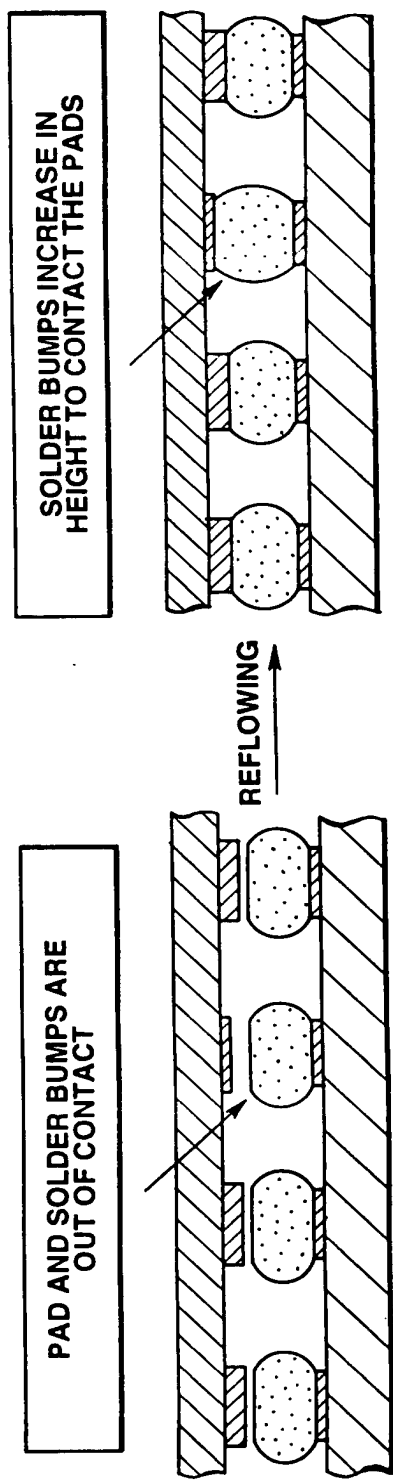


FIG.7





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FIG.8

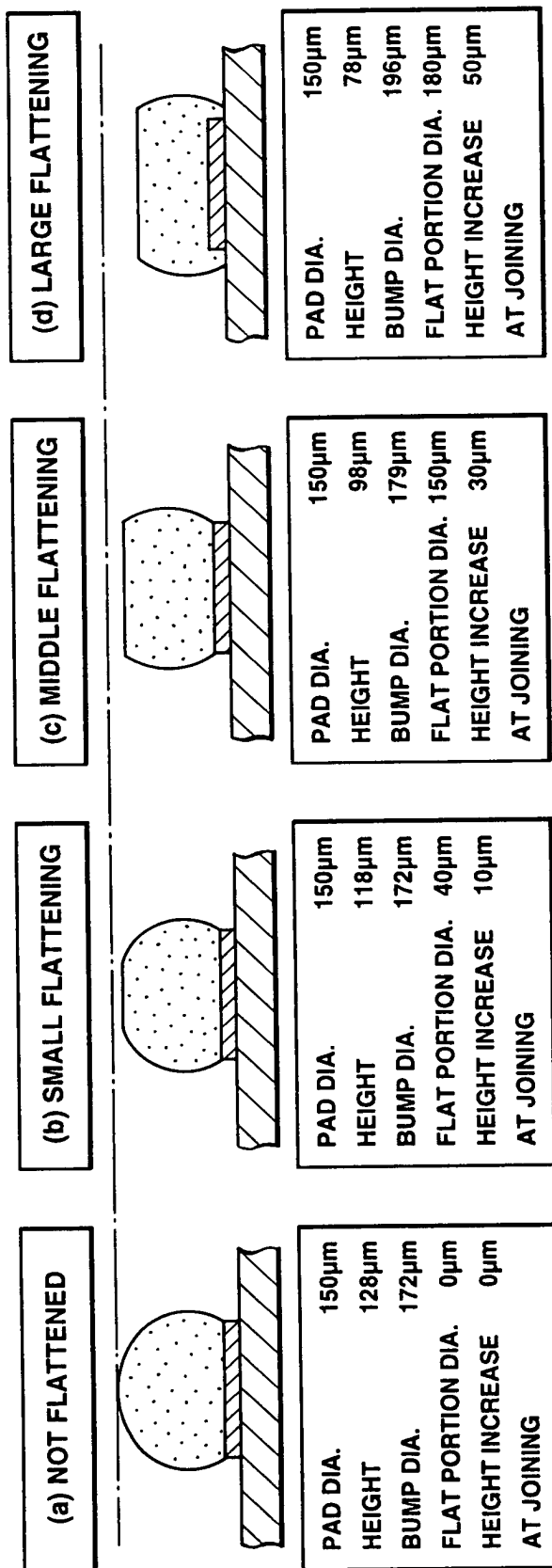




FIG.9

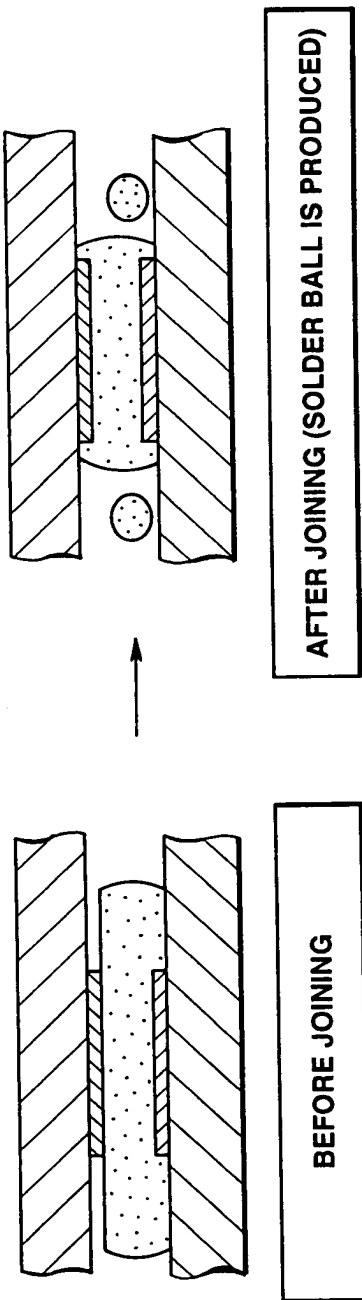


FIG.10

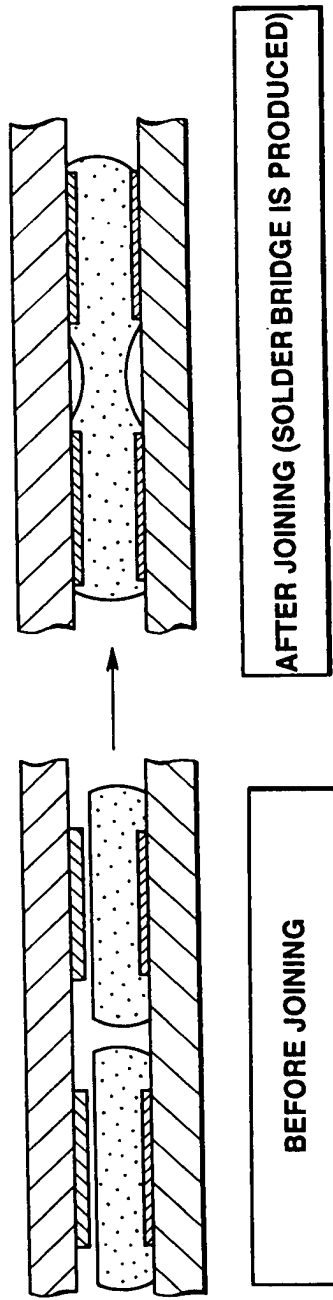






FIG.11A

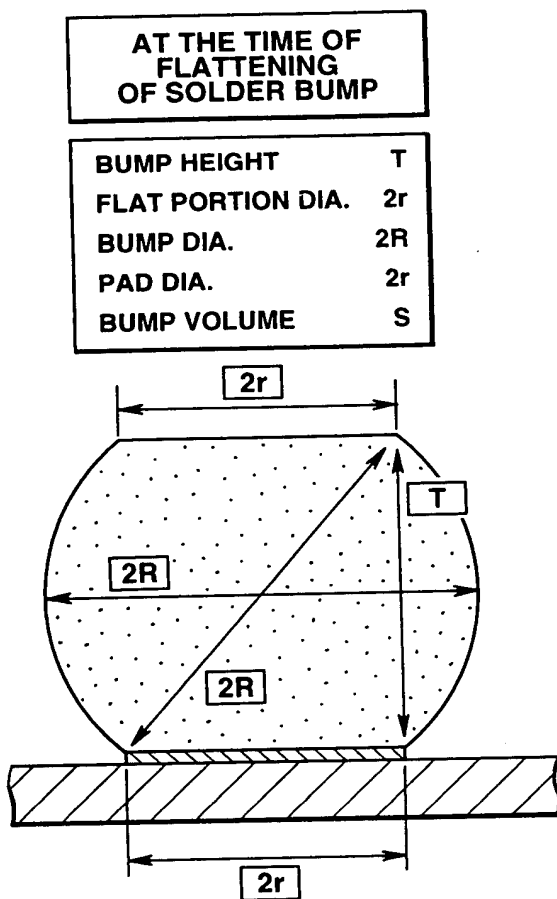
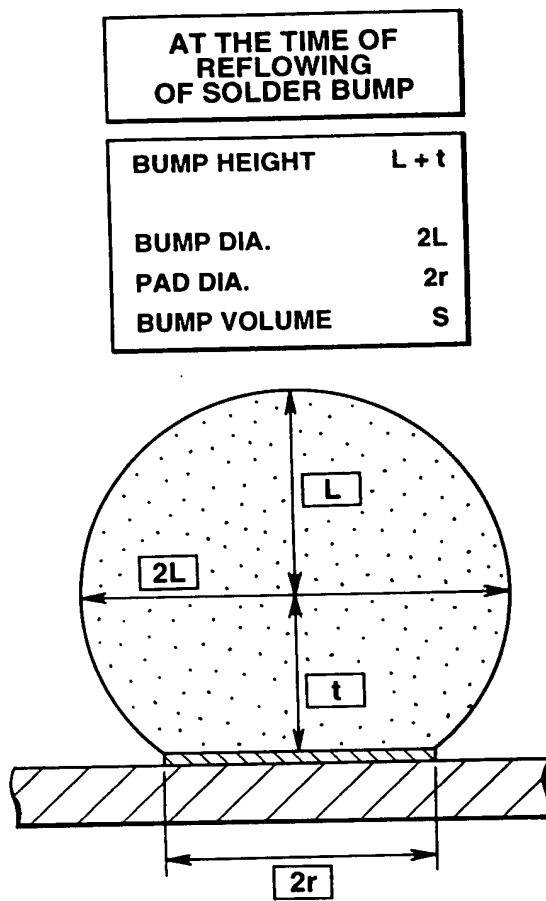


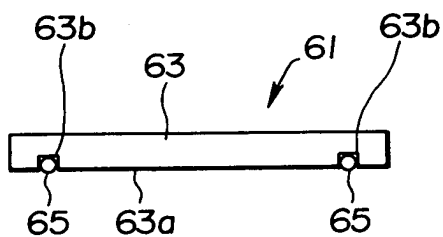
FIG.11B



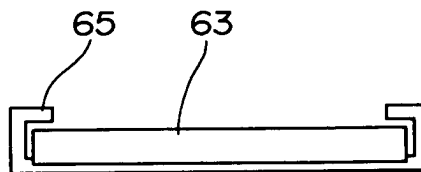


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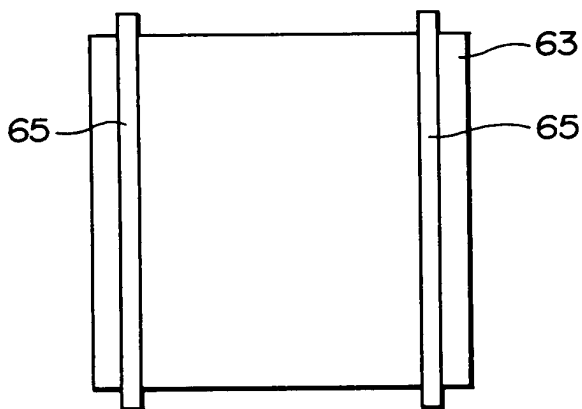
**FIG.12A**



**FIG.12C**



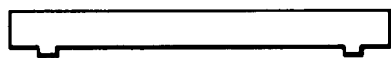
**FIG.12B**



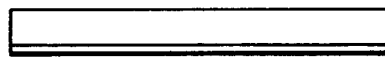


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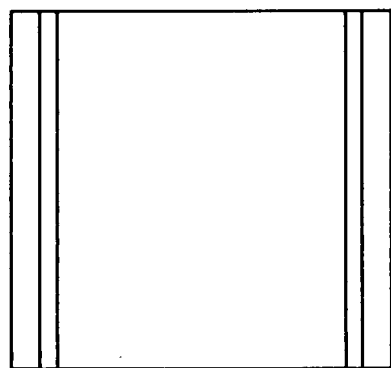
**FIG.13A**



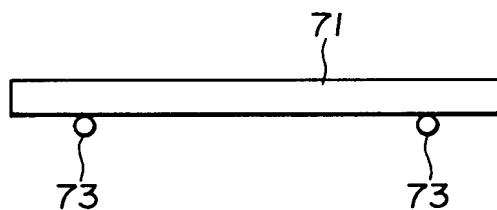
**FIG.13C**



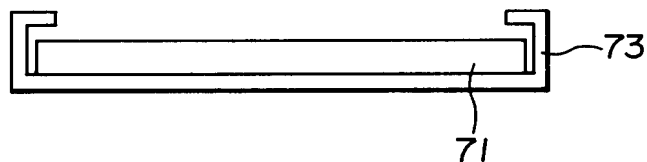
**FIG.13B**



**FIG.14A**

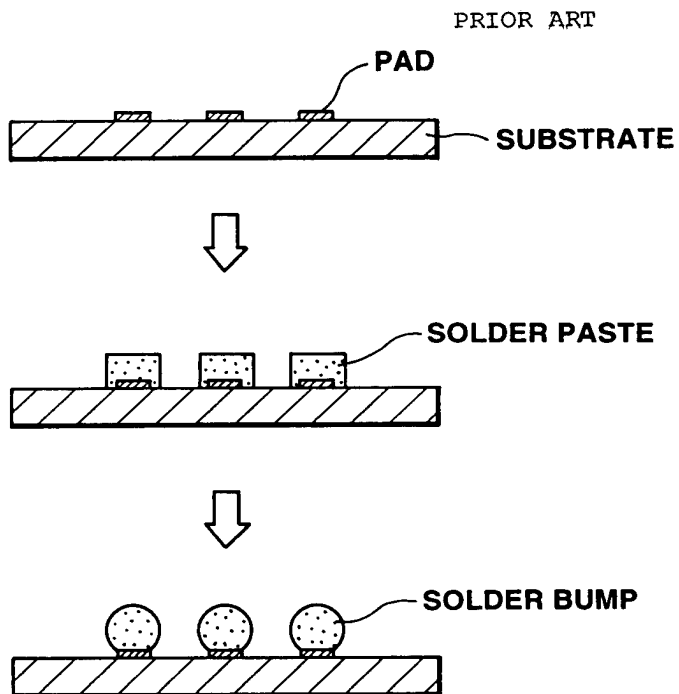


**FIG.14B**





**FIG.15A**



**FIG.15B**

